



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



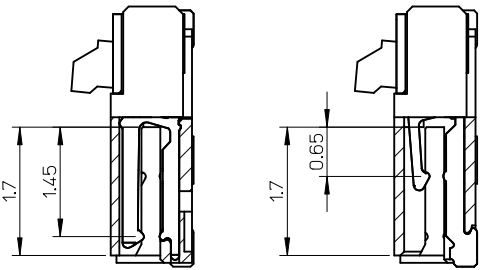
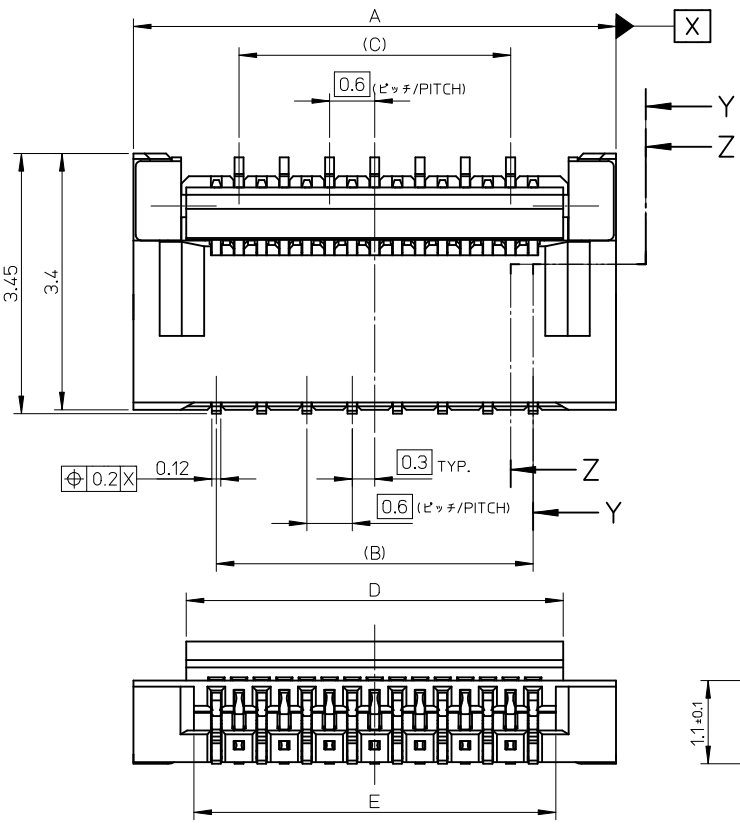
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

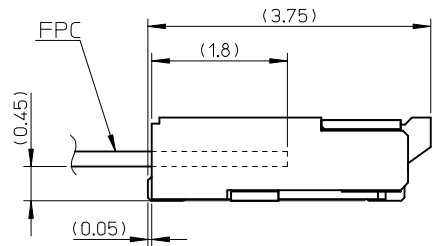
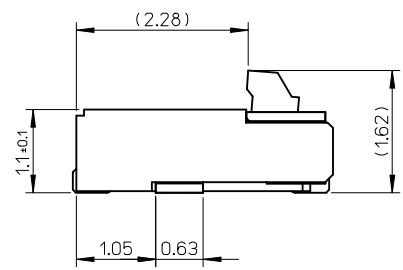
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





SECTION Z-Z

SECTION Y-Y



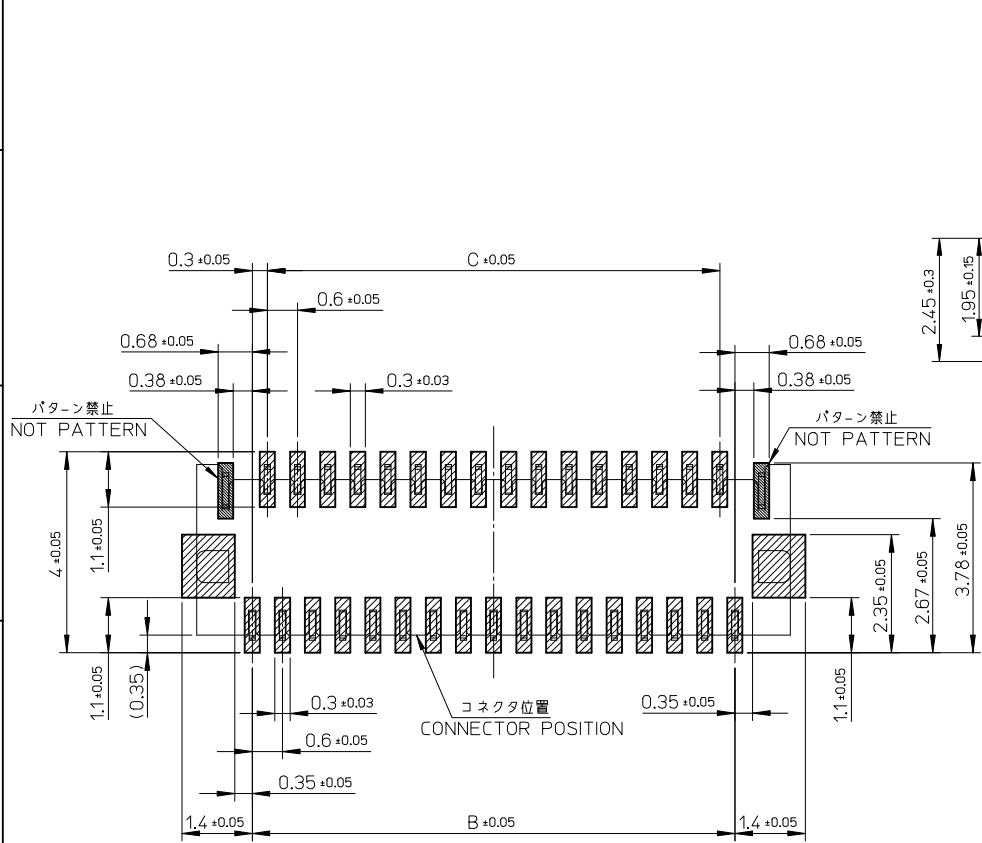
ACTUATOR CLOSE

部品構成

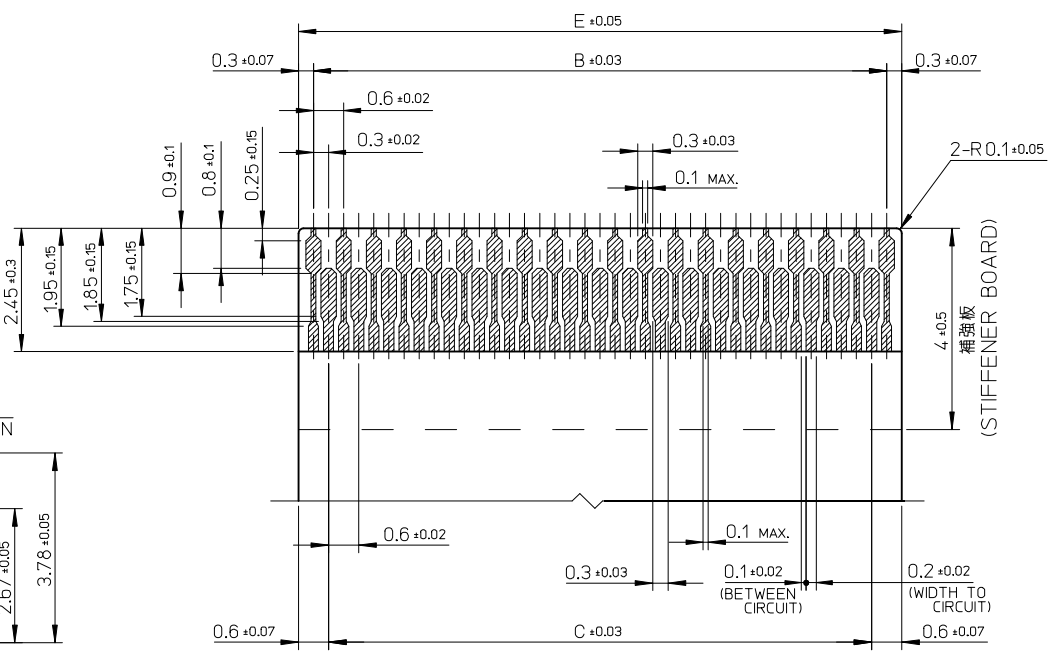
- ハウジング・・・材質：耐熱性樹脂 黒色 UL94V-0
HOUSING MATERIAL :HEAT RESISTANT POLYMER BLACK UL94-V0
- 奇数ターミナル・・・材質：銅合金
ODD TERMINAL MATERIAL :COPPER ALLOY
処理：ニッケル下地部分金メッキ（接触部及びテール部）
FINISH :PARTLY GOLD(CONTACT,TAIL) OVER NICKEL PLATING
- 偶数ターミナル・・・材質：銅合金
EVEN TERMINAL MATERIAL:COPPER ALLOY
処理：ニッケル下地部分金メッキ（接触部及びテール部）
FINISH :PARTLY GOLD(CONTACT,TAIL) OVER NICKEL PLATING
- アクチュエータ・・・材質：耐熱性樹脂 灰色 UL94V-0
ACTUATOR MATERIAL :HEAT RESISTANT POLYMER GRAY UL94-V0
- ネイル・・・材質：銅合金
NAIL MATERIAL:COPPER ALLOY
処理：ニッケル下地すずめっき
FINISH :TIN OVER NICKEL PLATING

| | | | | | | | |
|-----|-----|-----|-----|------|-------------------------|-------------|----------------------|
| 9.0 | 9.2 | 7.8 | 8.4 | 10.6 | 501616-2975 | 501616-2940 | 29 |
| 8.4 | 8.6 | 7.2 | 7.8 | 10.0 | 501616-2775 | 501616-2740 | 27 |
| 7.8 | 8.0 | 6.6 | 7.2 | 9.4 | 501616-2575 | 501616-2540 | 25 |
| 6.0 | 6.2 | 4.8 | 5.4 | 7.6 | 501616-1975 | 501616-1940 | 19 |
| E | D | (C) | (B) | A | EMBOSSED TAPE ORDER No. | | MATERIAL NO. CIRCUIT |

| | | | | | | | |
|---|---------------------------------------|--------------|---|------------|--|------------------------|------------------------|
| REVISED EC NO: J2015-1263 DRWN: TAKAHASHI 04 2015/03/27 CHKD: TAKAHASHI 2015/03/27 APPR: YNOGAWA 2015/03/30 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE 15:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | 0.25 UNDER | ±0.03 | DRAWN BY | DATE | TITLE | | |
| | 0.25 OVER 0.5 UNDER | ±0.05 | K. TAKAHASHI | 2006/07/28 | 0.3 FPC CONN. ZIF E/O HSG ASSY (H=1.1) | | |
| | 0.5 OVER 1.0 UNDER | ±0.1 | CHECKED BY | DATE | DOCUMENT NO. | | |
| | 1.0 OVER 10 UNDER | ±0.2 | H. HIRATA | 2006/07/28 | SD-501616-005 | | |
| 10 OVER 30 UNDER | ±0.25 | APPROVED BY | DATE | SHEET NO. | | | |
| 30 OVER | ±0.3 | M. SASAO | 2006/07/28 | 1 OF 2 | | | |
| ANGULAR ±3 ° | | MATERIAL NO. | | SEE CHART | | | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | SIZE A3 | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | |



参考基板レイアウト (マウント面)
P.C. BOARD PATTERN
DIM.(REF.)



適合FPC推奨寸法
仕上がり厚さ : 0.2±0.03
APPLY FPC
RECOMMENDED DIM.
THICKNESS : 0.2±0.03

| | | | | | |
|-----|-----|-----|----------------------------|--------------|---------|
| 9.0 | 7.8 | 8.4 | 501616-2975 | 501616-2940 | 29 |
| 8.4 | 7.2 | 7.8 | 501616-2775 | 501616-2740 | 27 |
| 7.8 | 6.6 | 7.2 | 501616-2575 | 501616-2540 | 25 |
| 6.0 | 4.8 | 5.4 | 501616-1975 | 501616-1940 | 19 |
| E | C | B | EMBOSSED TAPE ORDER No. | MATERIAL NO. | CIRCUIT |

注記

1. 基板実装前にアクチュエータを操作しないで下さい。
PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
必ず基板に実装し、FPCを挿入してからアクチュエータを操作して下さい。
PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON
THE SUBSTRATE AND MATING FPC.
2. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
3. 本製品は上面接触品です。下面接続で使用しないでください。
THIS CONNECTOR IS UPPER CONTACT TYPE.
PLEASE DO NOT USE AS LOWER CONTACT TYPE.

| | | | | | | |
|---|-------------|--|----------------------------|--------------------|--|---------------------------|
| REVISED EC NO: J2015-1263 DRW: M. TAKAHASHI 04/2015/03/27 CHK: D. TAKAHASHI 2015/03/27 APPR: Y. NOGAWA 2015/03/30 | DESCRIPTION | GENERAL TOLERANCES (UNLESS SPECIFIED) | DIMENSION STYLE MM ONLY | SCALE 10:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | REV | 0.25 UNDER ±0.03 0.25 OVER 0.5 UNDER ±0.05 0.5 OVER 1.0 UNDER ±0.1 1.0 OVER 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 ° | DRAWN BY K. TAKAHASHI | DATE 2006/07/28 | TITLE 0.3 FPC CONN. ZIF E/O HSG ASSY (H=1.1) | |
| | A | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | CHECKED BY H. HIRATA | DATE 2006/07/28 | DOCUMENT NO. molex SD-501616-005 | |
| | | SIZE A3 | APPROVED BY M. SASAO | DATE 2006/07/28 | | |

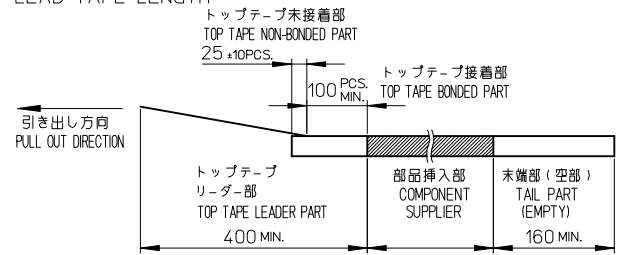
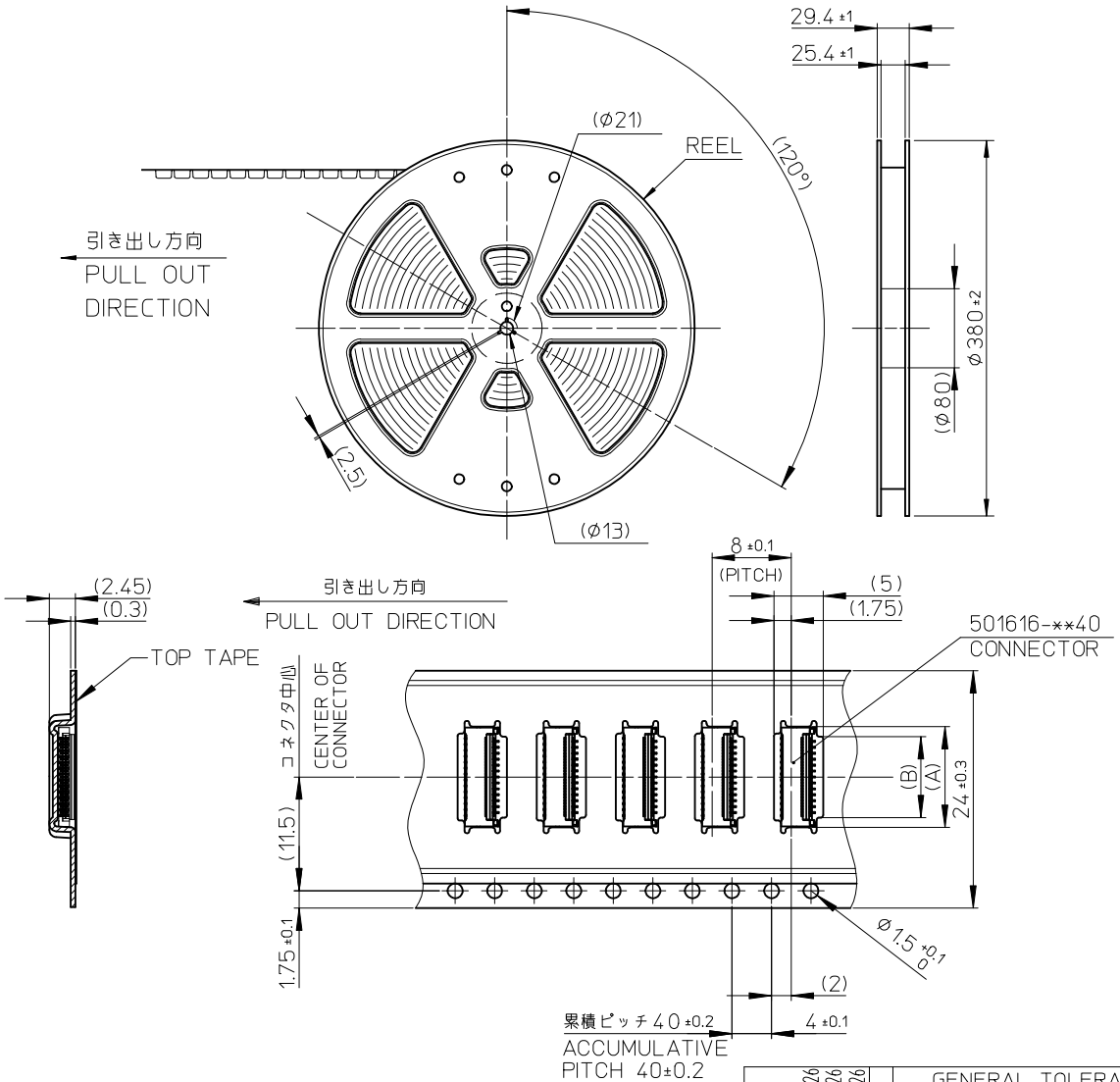
SEE CHART

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

NOTES

- 製品 (501616-**40) の詳細寸法については、
図面 SD-501616-005 をご参照下さい。
IN THE PACKAGE, PART NO. 501616-**40 DETAILED DIMENSIONS,
REFER TO SALES DRAWING NO. SD-501616-005.
- 梱包数量 : 3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH

| | | | |
|--|--|-----------------------------|---|
| トップテープ未接着部 TOP TAPE NON-BONDED PART 25 ±10PCS. | トップテープ接着部 TOP TAPE BONDED PART 100 PCS. MIN. | 部品挿入部 COMPONENT SUPPLIER | 未端部 (空部) TAIL PART (EMPTY) 160 MIN. |
| 400 MIN. | | | |
- 材料
キャリアテープ: ポリスチレン (PS)
トップテープ : PET, PE, PEF
リール : ポリスチレン (PS) <リサイクル材を含む>
MATERIAL
CARRIER TAPE : POLYSTYRENE (PS)
TOP TAPE : PET, PE, PEF
REEL : POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



| | | | |
|-----|------|------------------|---------|
| 8.8 | 10.8 | 501616-2975 | 29 |
| 8.2 | 10.2 | 501616-2775 | 27 |
| 7.6 | 9.6 | 501616-2575 | 25 |
| 5.8 | 7.8 | 501616-1975 | 19 |
| B | A | EMBOSSED PACKAGE | 極数 |
| | | オーダー番号 ORDER No. | CIRCUIT |

| | | | | | |
|--|---|----------------------------|-------------------|---|------------------------|
| REVISED EC NO: J2009-1784 DRWN:MKAWABATA 2009/01/26 CHKD:HSHINOYAMA 2009/01/26 APPR:HSHINOYAMA 2009/01/26 REV A | GENERAL TOLERANCES (UNLESS SPECIFIED) | DIMENSION STYLE MM ONLY | SCALE --- | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | 10 UNDER ± --- | DRAWN BY K. TAKAHASHI | DATE 2006/7/28 | TITLE 0.3 FPC CONN. B/F EMBSTP PKG H=1.1 | |
| | 10 OVER 30 UNDER ± --- | CHECKED BY H. HIRATA | DATE 2006/7/28 | MOLEX INCORPORATED | |
| | 30 OVER ± --- | APPROVED BY M. SASAO | DATE 2006/7/28 | DOCUMENT NO. SD-501616-006 | SHEET NO. 1 OF 1 |
| ANGULAR ± --- ° | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | SEE CHART | | |
| SIZE A3 | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | |